

HiTemp ET Series Thermoelectric Cooler

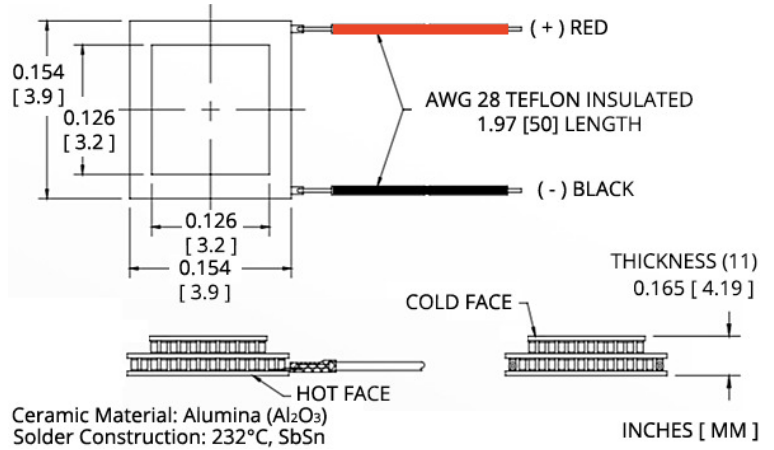
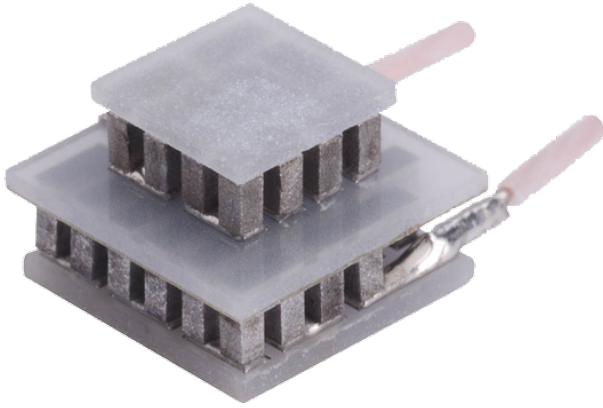
Note: This product is not recommended for new designs.
 This product series has been replaced with the HiTemp ETX Series. Currently there is no standard HiTemp ETX Series replacement for this part. Contact Sales for available options.

Features

- High-temperature operation
- Reliable solid-state
- No sound or vibration
- Environmentally-friendly
- RoHS-compliant

Applications

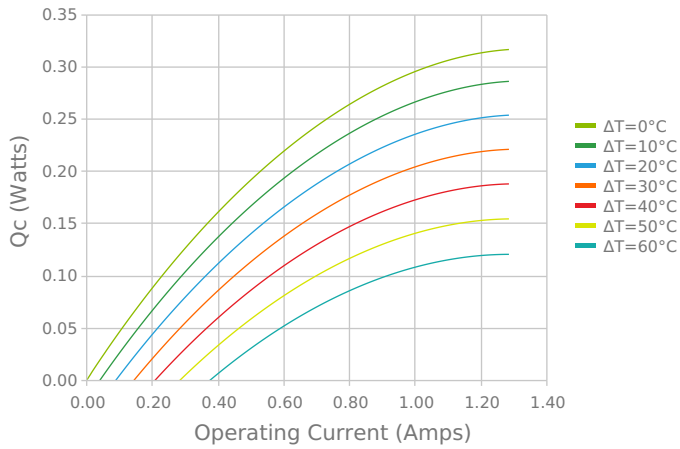
- Peltier Cooling for Refrigerated Centrifuges
- Peltier Cooling for Machine Vision
- Thermoelectric Cooling for CMOS Sensors
- Cooling Solutions for Autonomous Systems
- Peltier Cooling for Digital
- Light Processors



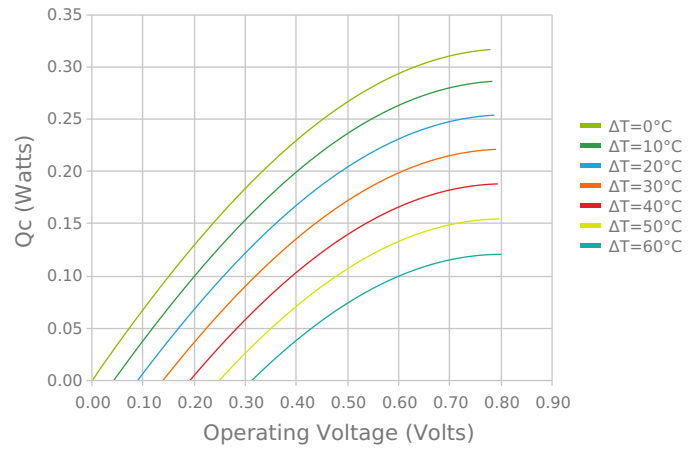
ELECTRICAL AND THERMAL PERFORMANCE

For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

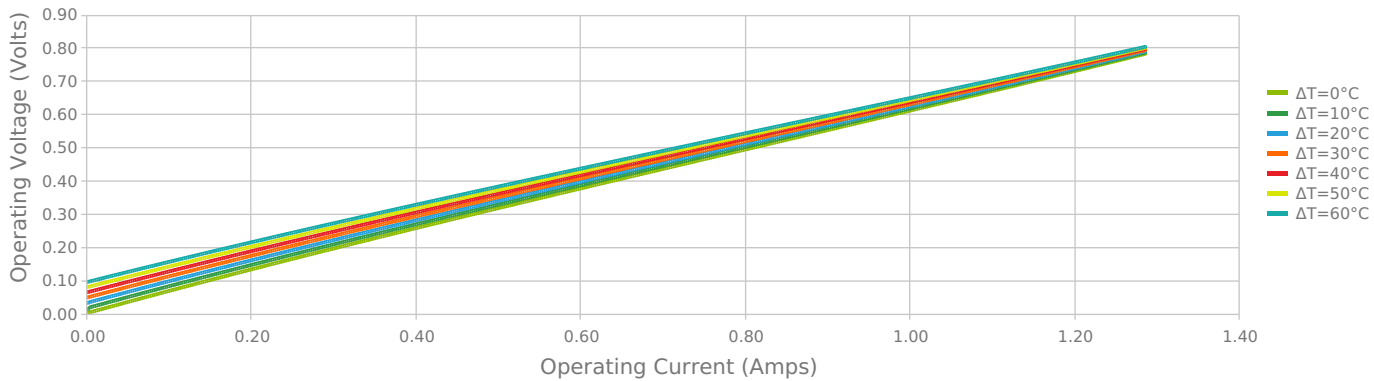
Heat Pumped at Cold Side
 Thot = 27 °C



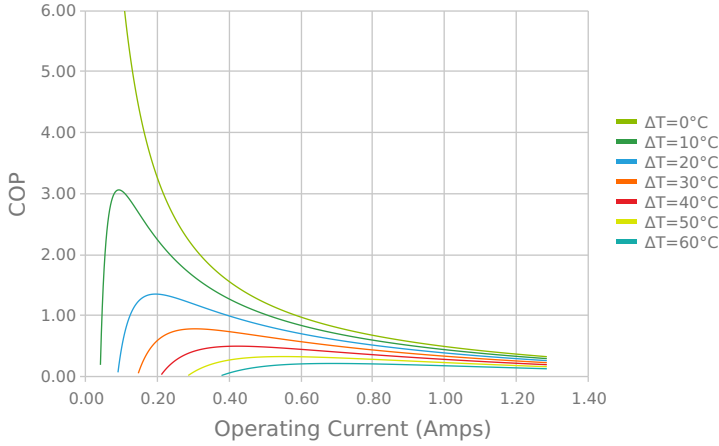
Heat Pumped at Cold Side
 Thot = 27 °C



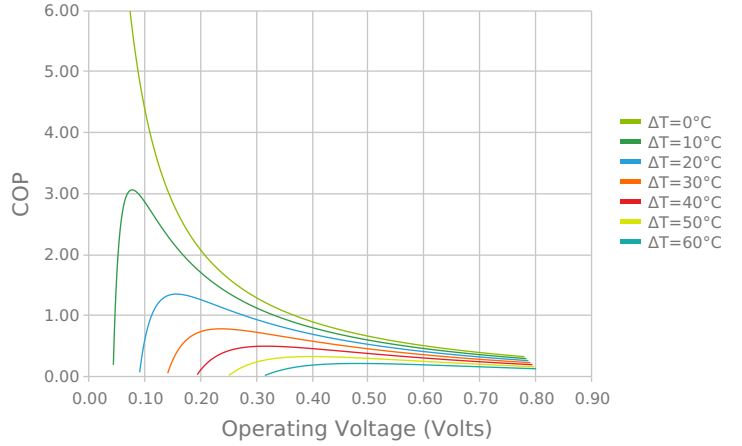
Current vs Voltage (I vs V)
 Thot = 27 °C



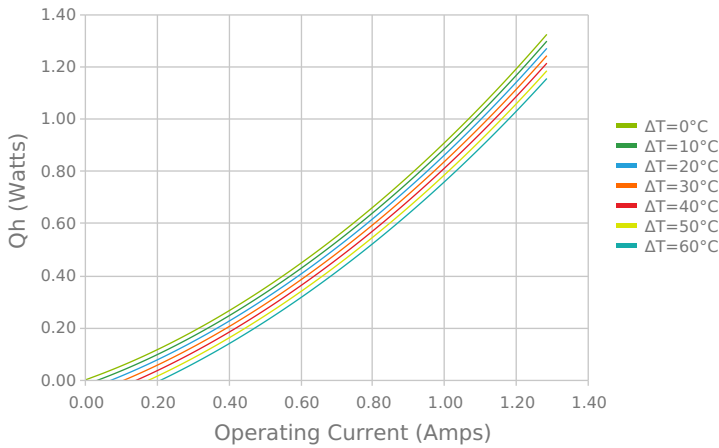
Coefficient of Performance (COP = Qc/Pin)
 Thot = 27 °C



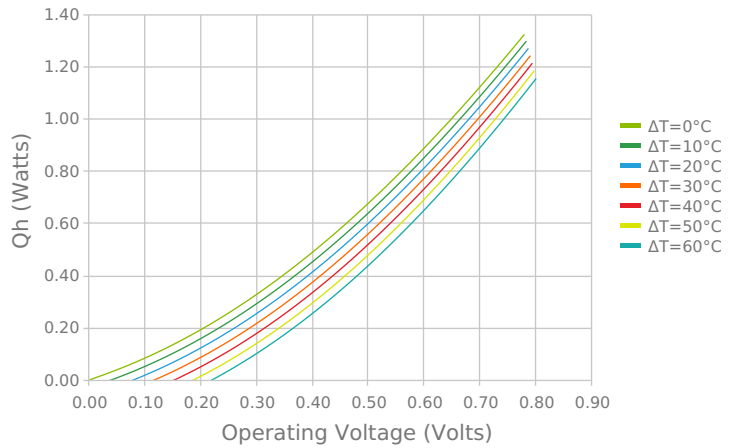
Coefficient of Performance (COP = Qc/Pin)
 Thot = 27 °C



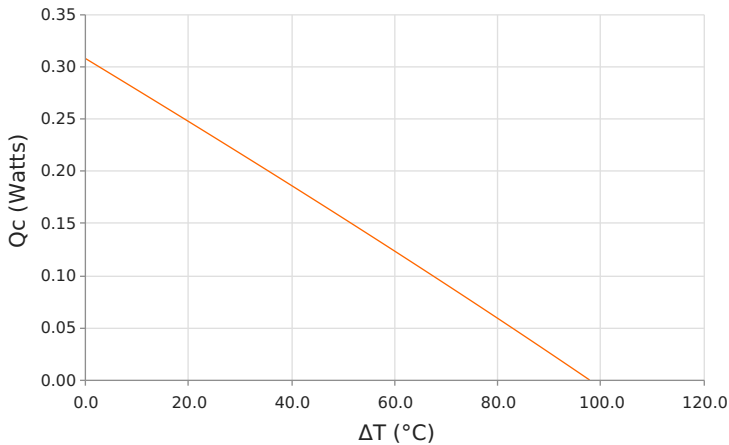
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)
 Thot = 27 °C



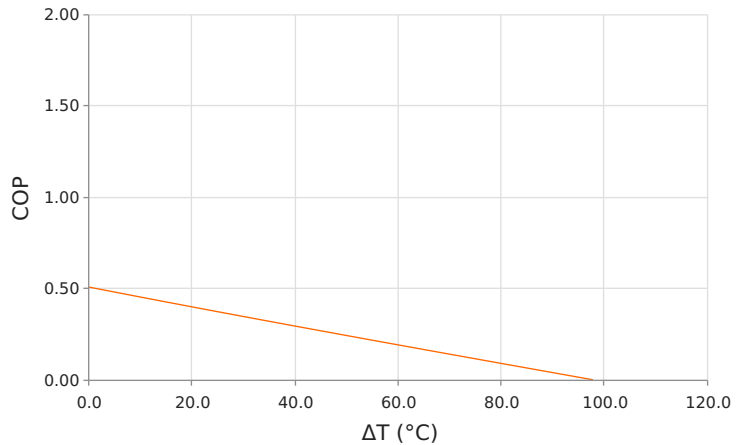
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)
 Thot = 27 °C



Heat Pumped at Cold Side (Qc)
 Thot = 27 °C | Current = 1.0 Amps



Coefficient of Performance (COP = Qc/Pin)
 Thot = 27 °C | Current = 1.0 Amps



SPECIFICATIONS*

Hot Side Temperature	27.0 °C
Qcmax ($\Delta T = 0$)	0.3 Watts
ΔT_{max} ($Q_c = 0$)	93.0 °C
I_{max} (I @ ΔT_{max})	1.2 Amps
V_{max} (V @ ΔT_{max})	0.8 Volts
Module Resistance	0.62 Ohms
Max Operating Temperature	150 °C
Weight	1.0 gram(s)

* Specifications reflect thermoelectric coefficients updated March 2020

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
11	4.200 ± 0.203 mm 0.165 ± 0.008 in	0.025 mm / 0.203 mm 0.001 in / 0.008 in	Lapped	Lapped	199.9 mm 7.87 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description

NOTES

1. Max operating temperature: 150°C
2. Do not exceed I_{max} or V_{max} when operating module
3. Reference assembly guidelines for recommended installation
4. Solder tinning also available on metallized ceramics

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